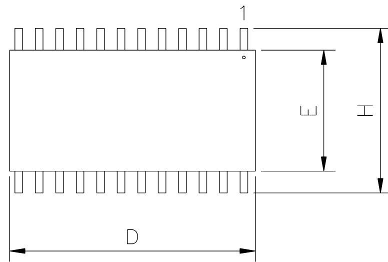
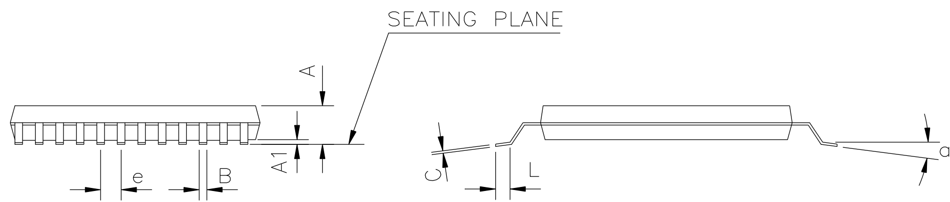
300 MIL SSOP
SHRINK SMALL OUTLINE PACKAGE

PACKAGE INFORMATION



NOTES

1. LEAD WIDTH AND LEAD THICKNESS EXCLUSIVE OF SOLDER PLATE
2. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASHES AND BURR DIMENSIONS
3. ALLOWABLE MOLD FLASH IS 5 MILS PER SIDE.
4. DIMENSIONS ARE GIVEN IN INCHES.
5. LEAD COPLANARITY IS 0.003 INCH MAX.



JEDEC #	MO-118AA		MO-118AB	
TYPE	48 LEAD		56 LEAD	
SYMBOL	Min	Max	Min	Max
A	0.095	0.110	0.095	0.110
A1	0.008	0.016	0.008	0.016
B	0.008	0.012	0.008	0.0135
C	0.005	0.009	0.005	0.010
D	0.620	0.630	0.720	0.730
E	0.291	0.299	0.291	0.299
e	0.025BSC		0.025BSC	
H	0.395	0.420	0.395	0.420
L	0.020	0.040	0.020	0.040
a°	0°	8°	0°	8°

PREPARED BY	NK	REF. NO.	REV. NO.
CHECKED BY	SP	DIM-SSOP-01	1
APPROVED BY	NJC		DATE 01.07.01

SPEL SEMICONDUCTOR LIMITED
INDIA